

$V_{DSS}$	1200V
$R_{DS(on)}$ (Typ.)	105mΩ
$I_D^{*1}$	24A
$P_D$	134W

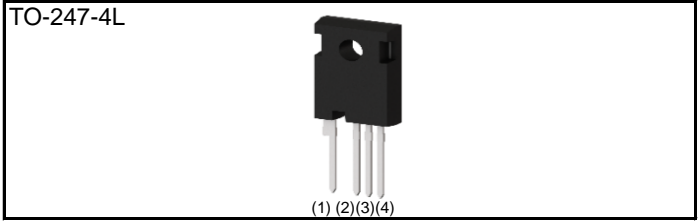
#### ●Features

- 1) Low on-resistance
- 2) Fast switching speed
- 3) Fast reverse recovery
- 4) Easy to parallel
- 5) Simple to drive
- 6) Pb-free lead plating ; RoHS compliant

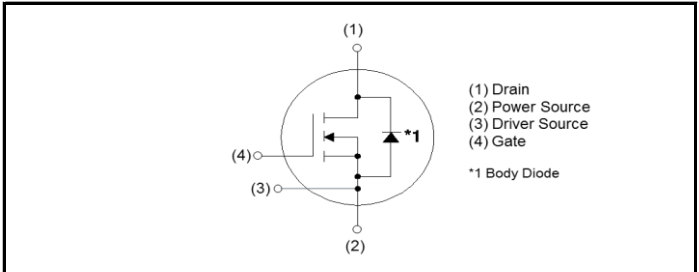
#### ●Application

- Solar inverters
- DC/DC converters
- Switch mode power supplies
- Induction heating
- Motor drives

#### ●Outline



#### ●Inner circuit



Please note Driver Source and Power Source are not exchangeable. Their exchange might lead to malfunction.

#### ●Packaging specifications

Type	Packing	Tube
	Reel size (mm)	-
	Tape width (mm)	-
	Basic ordering unit (pcs)	30
	Taping code	C14
	Marking	SCT3105KR

#### ●Absolute maximum ratings ( $T_a = 25^\circ\text{C}$ )

Parameter	Symbol	Value	Unit
Drain - Source Voltage	$V_{DSS}$	1200	V
Continuous Drain current	$T_c = 25^\circ\text{C}$	$I_D^{*1}$	24
	$T_c = 100^\circ\text{C}$	$I_D^{*1}$	17
Pulsed Drain current	$I_{D,pulse}^{*2}$	60	A
Gate - Source voltage (DC)	$V_{GSS}$	-4 to +22	V
Gate - Source surge voltage ( $t_{surge} < 300\text{ns}$ )	$V_{GSS,surge}^{*3}$	-4 to +26	V
Recommended drive voltage	$V_{GS,op}^{*4}$	0 / +18	V
Junction temperature	$T_j$	175	$^\circ\text{C}$
Range of storage temperature	$T_{stg}$	-55 to +175	$^\circ\text{C}$

**●Electrical characteristics** ( $T_a = 25^\circ\text{C}$ )

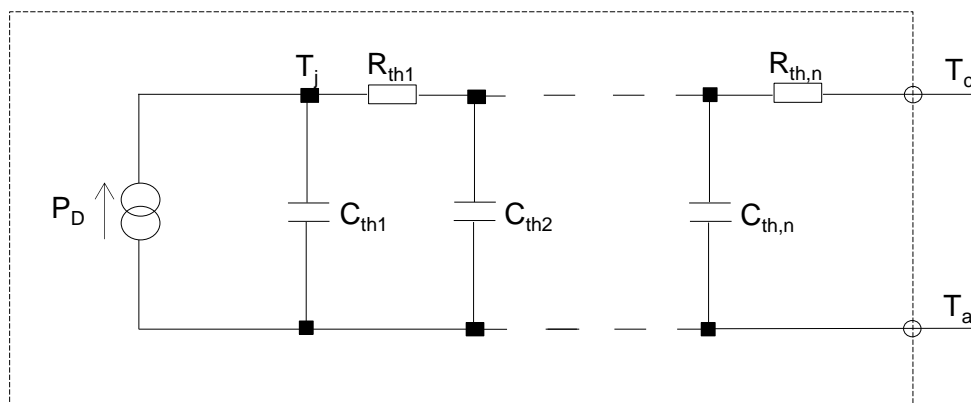
Parameter	Symbol	Conditions	Values			Unit
			Min.	Typ.	Max.	
Drain - Source breakdown voltage	$V_{(BR)DSS}$	$V_{GS} = 0\text{V}, I_D = 1\text{mA}$ $T_j = 25^\circ\text{C}$ $T_j = -55^\circ\text{C}$	1200 1200	- -	- -	V
Zero Gate voltage Drain current	$I_{DSS}$	$V_{GS} = 0\text{V}, V_{DS} = 1200\text{V}$ $T_j = 25^\circ\text{C}$ $T_j = 150^\circ\text{C}$	- -	1 2	10 -	$\mu\text{A}$
Gate - Source leakage current	$I_{GSS+}$	$V_{GS} = +22\text{V}, V_{DS} = 0\text{V}$	-	-	100	nA
Gate - Source leakage current	$I_{GSS-}$	$V_{GS} = -4\text{V}, V_{DS} = 0\text{V}$	-	-	-100	nA
Gate threshold voltage	$V_{GS(th)}$	$V_{DS} = 10\text{V}, I_D = 3.81\text{mA}$	2.7	-	5.6	V
Static Drain - Source on - state resistance	$R_{DS(on)}^{*5}$	$V_{GS} = 18\text{V}, I_D = 7.6\text{A}$ $T_j = 25^\circ\text{C}$ $T_j = 150^\circ\text{C}$	- -	105 179	137 -	m $\Omega$
Gate input resistance	$R_G$	$f = 1\text{MHz}, \text{open drain}$	-	13	-	$\Omega$

**●Thermal resistance**

Parameter	Symbol	Values			Unit
		Min.	Typ.	Max.	
Thermal resistance, junction - case	$R_{thJC}$	-	0.86	1.12	$^\circ\text{C/W}$

**●Typical Transient Thermal Characteristics**

Symbol	Value	Unit	Symbol	Value	Unit
$R_{th1}$	$1.14 \times 10^{-1}$	K/W	$C_{th1}$	$5.02 \times 10^{-4}$	Ws/K
$R_{th2}$	$5.07 \times 10^{-1}$		$C_{th2}$	$4.91 \times 10^{-3}$	
$R_{th3}$	$2.51 \times 10^{-1}$		$C_{th3}$	$4.99 \times 10^{-2}$	



●Electrical characteristics ( $T_a = 25^\circ\text{C}$ )

Parameter	Symbol	Conditions	Values			Unit
			Min.	Typ.	Max.	
Transconductance	$g_{fs}^{*5}$	$V_{DS} = 10\text{V}, I_D = 7.6\text{A}$	-	3.4	-	S
Input capacitance	$C_{iss}$	$V_{GS} = 0\text{V}$	-	574	-	pF
Output capacitance	$C_{oss}$	$V_{DS} = 800\text{V}$	-	59	-	
Reverse transfer capacitance	$C_{rss}$	$f = 1\text{MHz}$	-	28	-	
Effective output capacitance, energy related	$C_{o(er)}$	$V_{GS} = 0\text{V}$ $V_{DS} = 0\text{V to } 600\text{V}$	-	159	-	pF
Total Gate charge	$Q_g^{*5}$	$V_{DS} = 600\text{V}$ $I_D = 7.6\text{A}$	-	51	-	nC
Gate - Source charge	$Q_{gs}^{*5}$	$V_{GS} = 18\text{V}$	-	10	-	
Gate - Drain charge	$Q_{gd}^{*5}$	See Fig. 1-1.	-	25	-	
Turn - on delay time	$t_{d(on)}^{*5}$	$V_{DS} = 600\text{V}$ $I_D = 7.6\text{A}$	-	4	-	ns
Rise time	$t_r^{*5}$	$V_{GS} = 0\text{V}/+18\text{V}$	-	12	-	
Turn - off delay time	$t_{d(off)}^{*5}$	$R_G = 0\Omega, L = 750\mu\text{H}$ $L_\sigma = 50\text{nH}, C_\sigma = 10\text{pF}$	-	16	-	
Fall time	$t_f^{*5}$	See Fig. 2-1, 2-2, 2-3.	-	10	-	
Turn - on switching loss	$E_{on}^{*5}$	$E_{on}$ includes diode reverse recovery.	-	125	-	$\mu\text{J}$
Turn - off switching loss	$E_{off}^{*5}$		-	8	-	

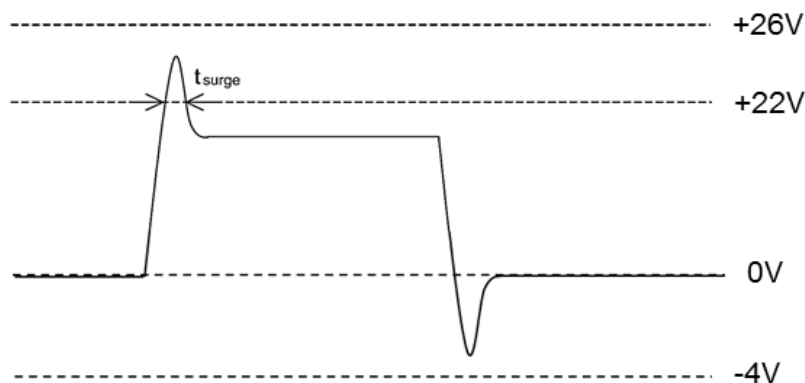
**●Body diode electrical characteristics (Source-Drain) ( $T_a = 25^\circ\text{C}$ )**

Parameter	Symbol	Conditions	Values			Unit
			Min.	Typ.	Max.	
Body diode continuous, forward current	$I_S$ *1	$T_c = 25^\circ\text{C}$	-	-	24	A
Body diode direct current, pulsed	$I_{SM}$ *2		-	-	60	A
Forward voltage	$V_{SD}$ *5	$V_{GS} = 0\text{V}, I_D = 7.6\text{A}$	-	3.2	-	V
Reverse recovery time	$t_{rr}$ *5	$I_F = 7.6\text{A}$ $V_R = 600\text{V}$ $di/dt = 2500\text{A}/\mu\text{s}$	-	13	-	ns
Reverse recovery charge	$Q_{rr}$ *5		-	175	-	nC
Peak reverse recovery current	$I_{rrm}$ *5	$L_\sigma = 50\text{nH}, C_\sigma = 10\text{pF}$ See Fig. 3-1, 3-2.	-	22	-	A

\*1 Limited by maximum temperature allowed.

\*2  $P_W \leq 10\mu\text{s}$ , Duty cycle  $\leq 1\%$

\*3 Example of acceptable  $V_{GS}$  waveform



Please note especially when using driver source that  $V_{GSS\_surge}$  must be in the range of absolute maximum rating.

\*4 Please be advised not to use SiC-MOSFETs with  $V_{GS}$  below 13V as doing so may cause thermal runaway.

\*5 Pulsed

●Electrical characteristic curves

Fig.1 Power Dissipation Derating Curve

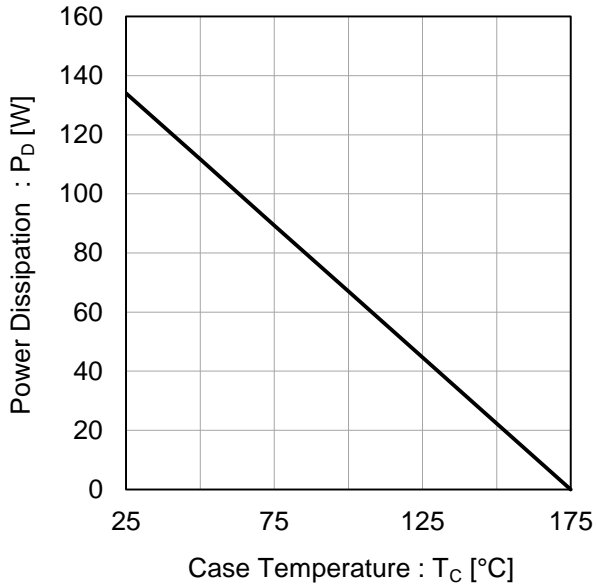


Fig.2 Maximum Safe Operating Area

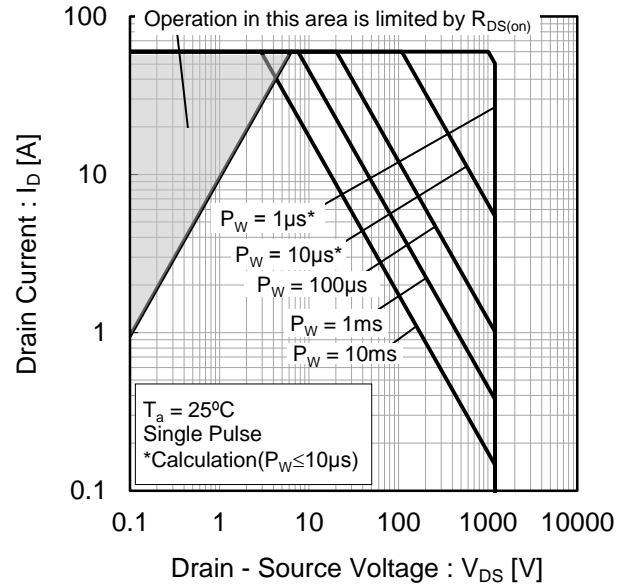
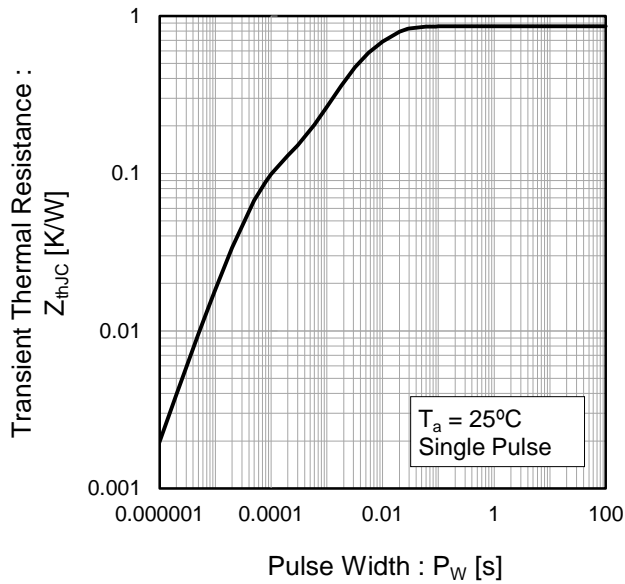


Fig.3 Typical Transient Thermal Resistance vs. Pulse Width



●Electrical characteristic curves

Fig.4 Typical Output Characteristics(I)

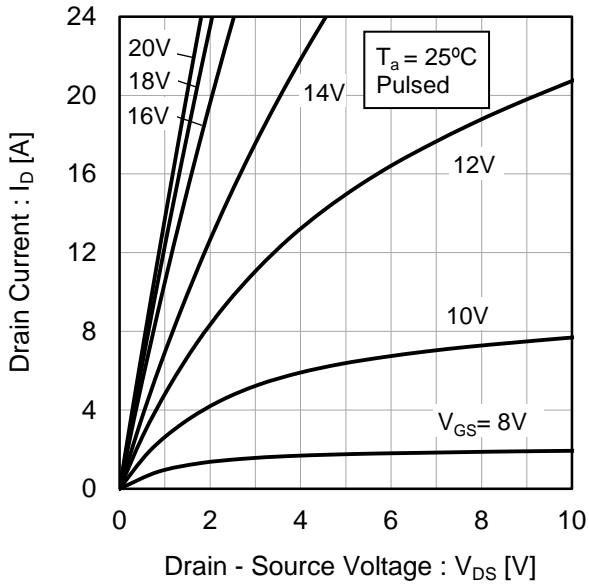


Fig.5 Typical Output Characteristics(II)

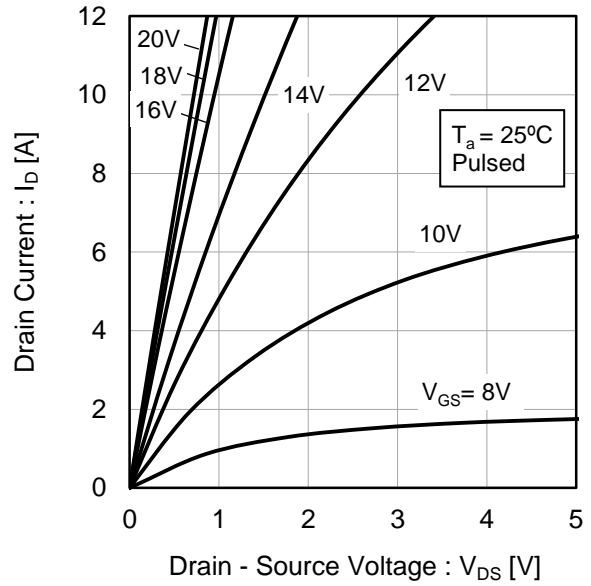
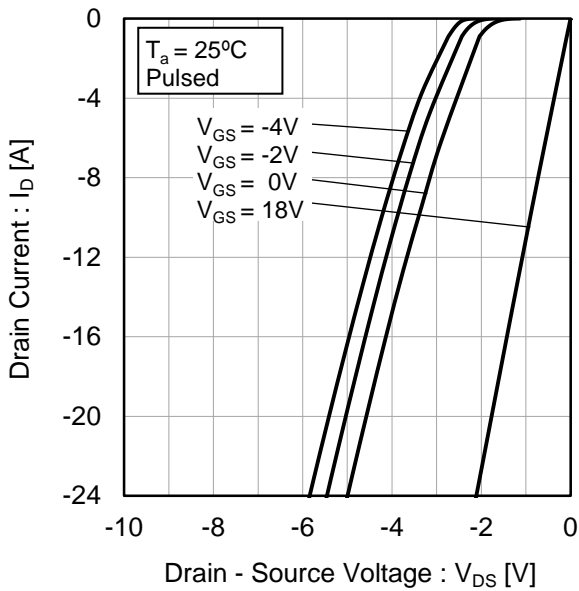


Fig.6  $T_j = 25^\circ\text{C}$  3rd Quadrant Characteristics



●Electrical characteristic curves

Fig.7  $T_j = 150^{\circ}\text{C}$  Typical Output Characteristics(I)

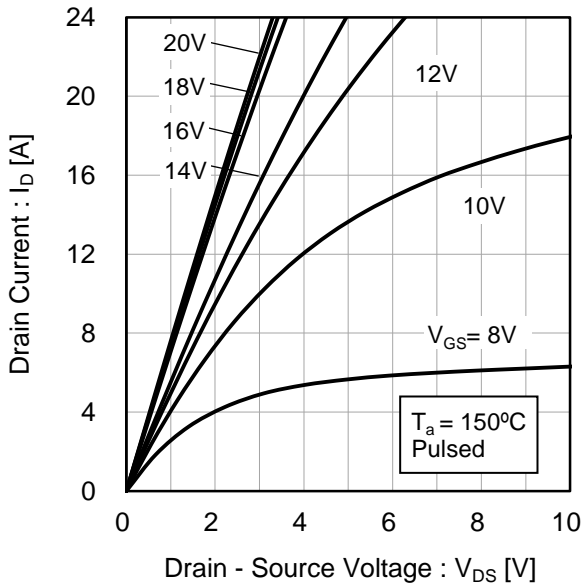


Fig.8  $T_j = 150^{\circ}\text{C}$  Typical Output Characteristics(II)

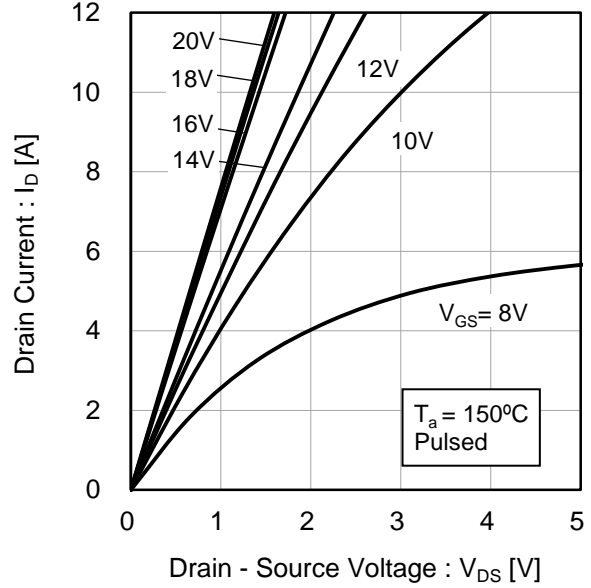


Fig.9  $T_j = 150^{\circ}\text{C}$  3rd Quadrant Characteristics

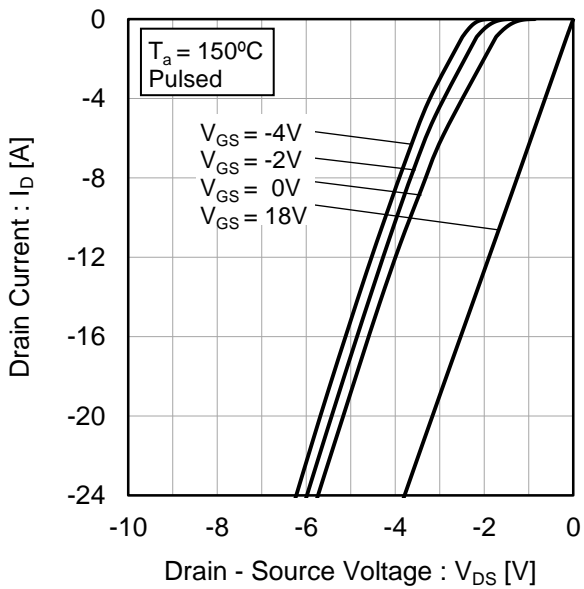
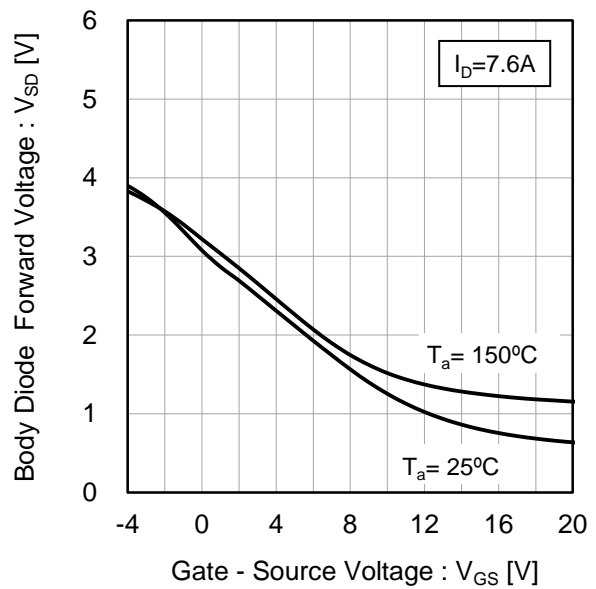


Fig.10 Body Diode Forward Voltage vs. Gate - Source Voltage



●Electrical characteristic curves

Fig.11 Typical Transfer Characteristics (I)

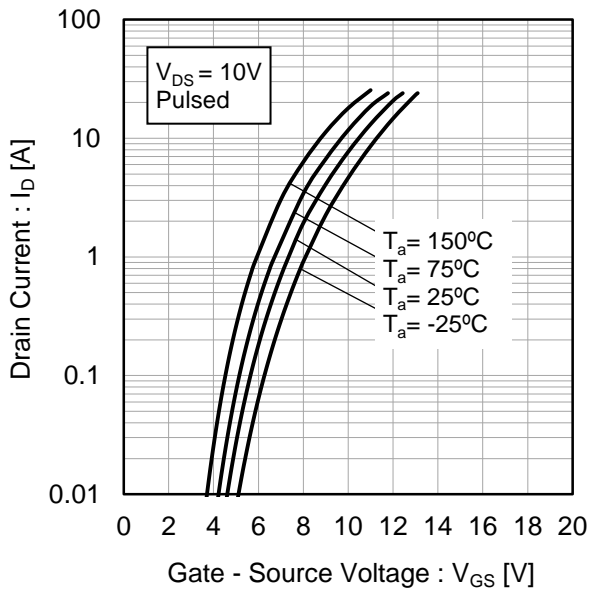


Fig.12 Typical Transfer Characteristics (II)

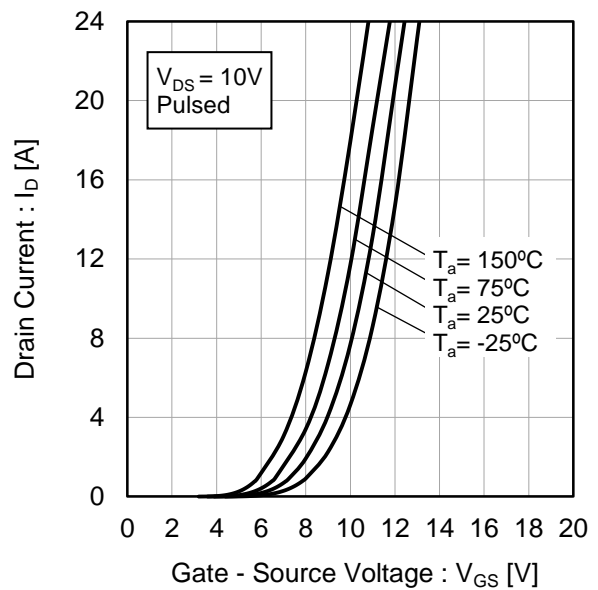


Fig.13 Gate Threshold Voltage vs. Junction Temperature

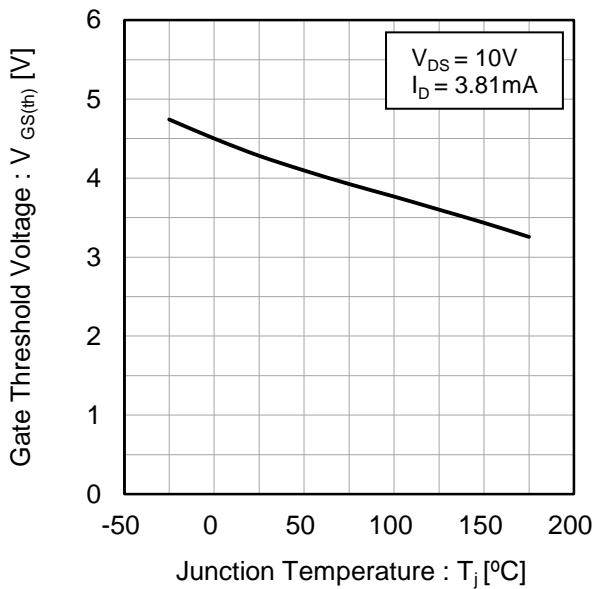
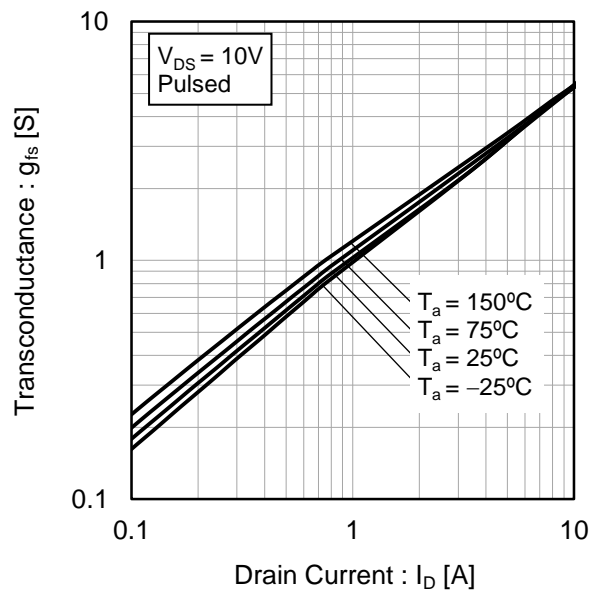


Fig.14 Transconductance vs. Drain Current





●Electrical characteristic curves

Fig.15 Static Drain - Source On - State Resistance vs. Gate - Source Voltage

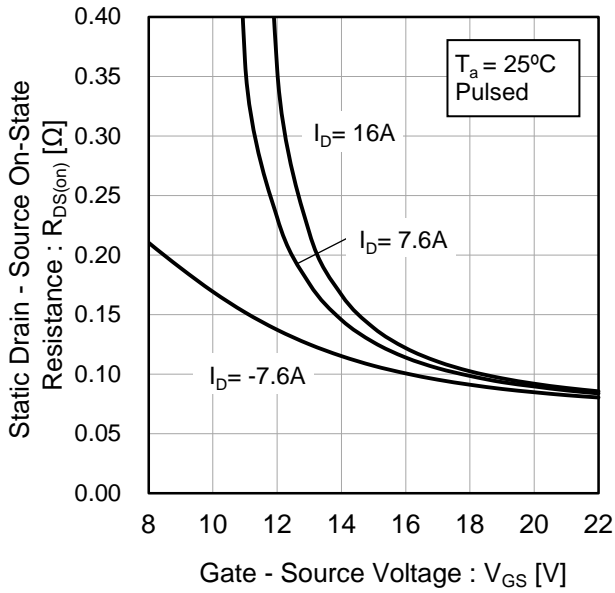


Fig.16 Static Drain - Source On - State Resistance vs. Junction Temperature

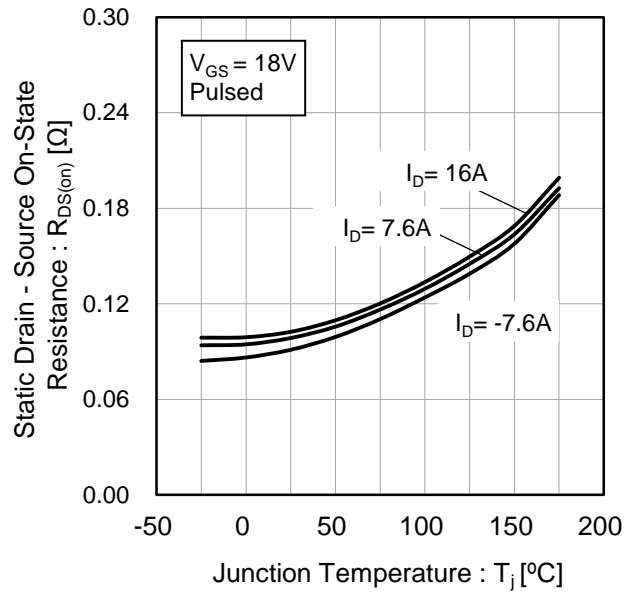


Fig.17 Static Drain - Source On - State Resistance vs. Drain Current

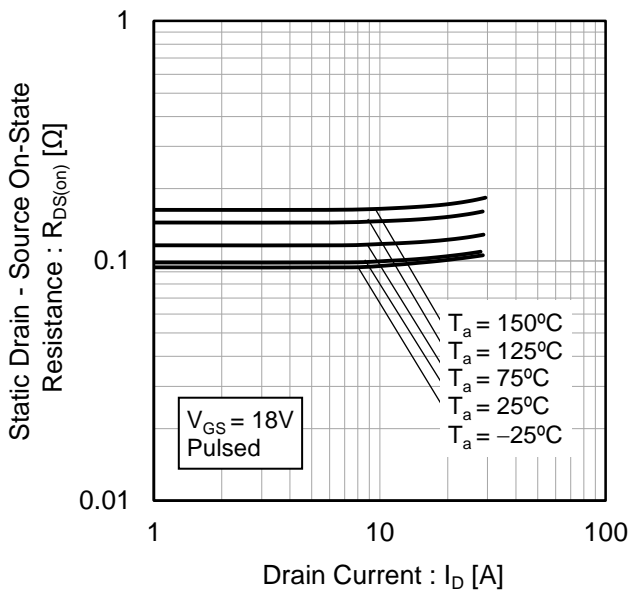
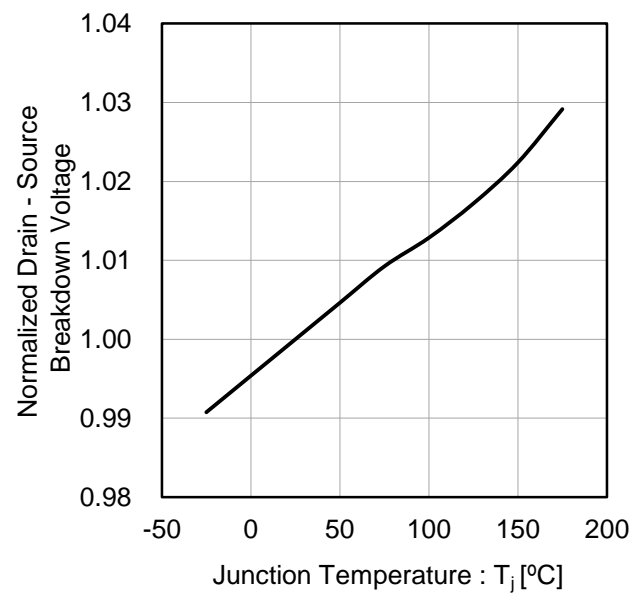


Fig.18 Normalized Drain - Source Breakdown Voltage vs. Junction Temperature



●Electrical characteristic curves

Fig.19 Typical Capacitance vs. Drain - Source Voltage

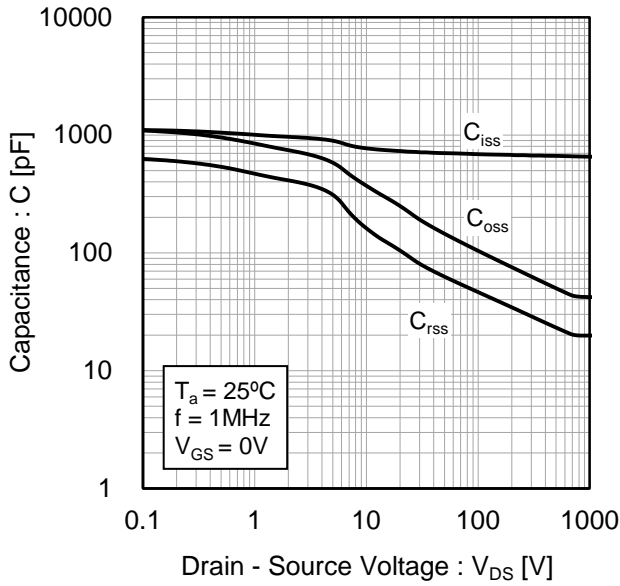


Fig.20 C<sub>oss</sub> Stored Energy

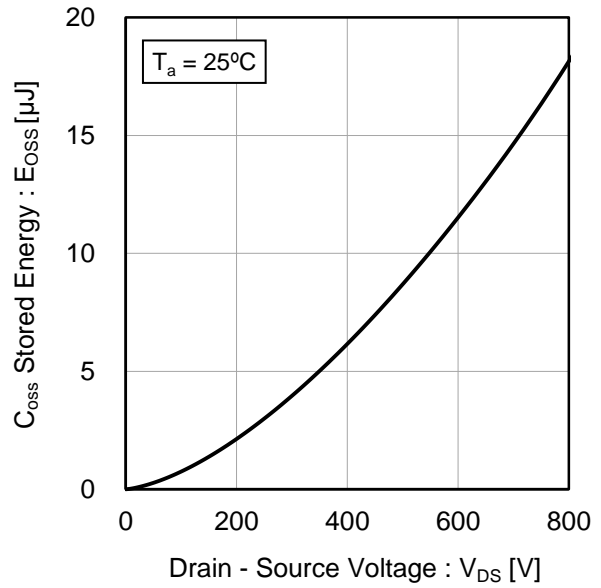
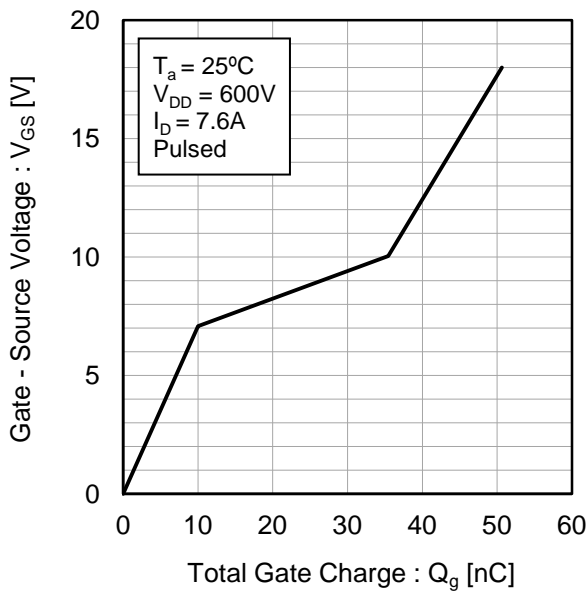
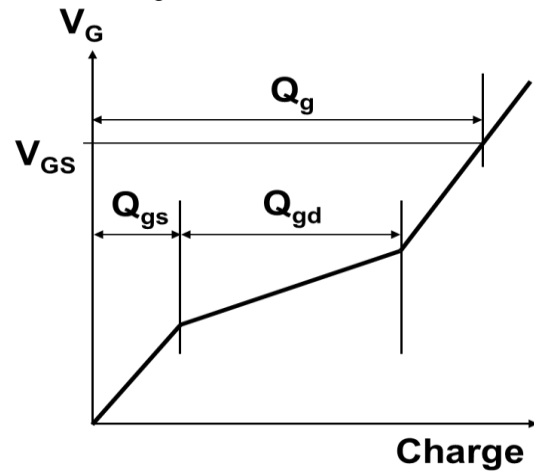


Fig.21 Dynamic Input Characteristics



\*Gate Charge Waveform



●Electrical characteristic curves

Fig.22 Typical Switching Time vs. External Gate Resistance

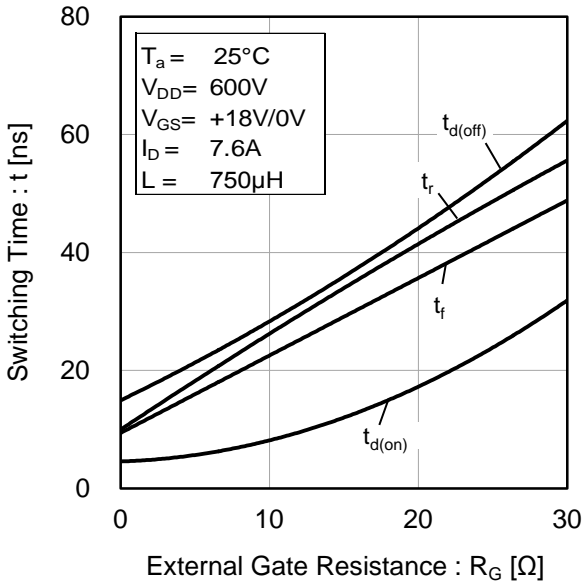


Fig.23 Typical Switching Loss vs. Drain - Source Voltage

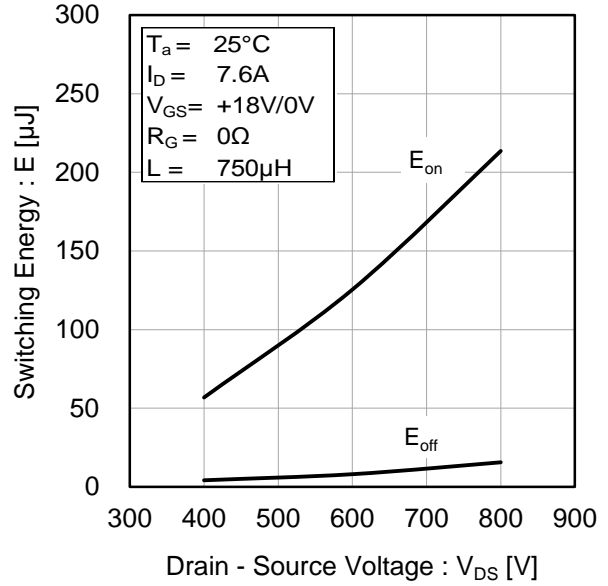


Fig.24 Typical Switching Loss vs. Drain Current

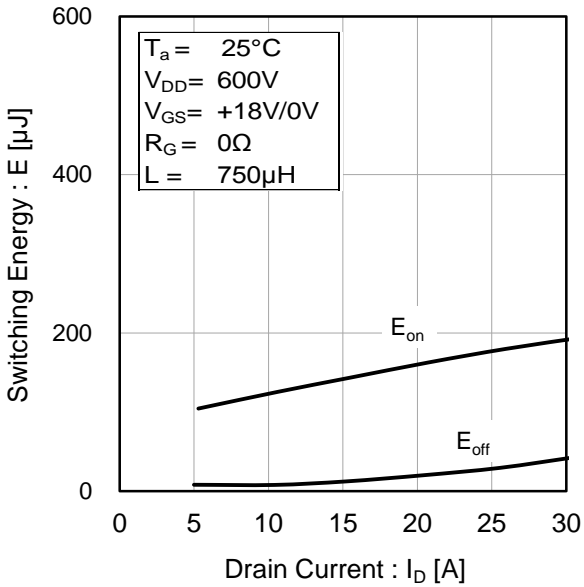
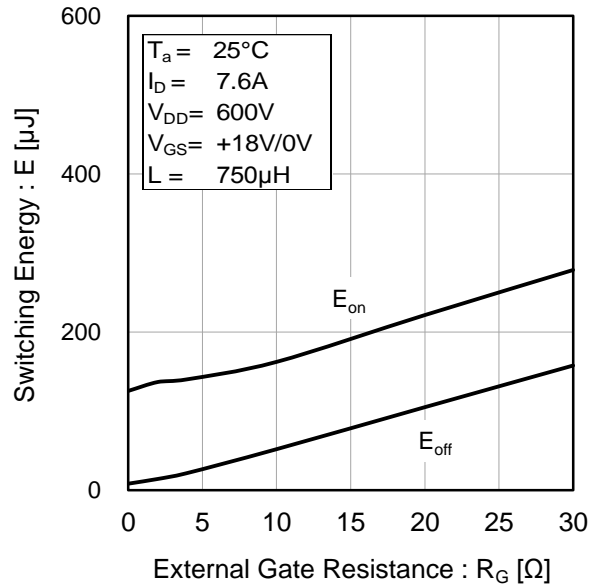


Fig.25 Typical Switching Loss vs. External Gate Resistance



● Measurement circuits and waveforms

Fig.1-1 Gate Charge Measurement Circuit

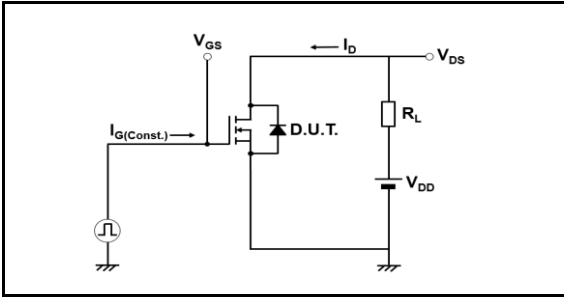


Fig.2-1 Switching Characteristics Measurement Circuit

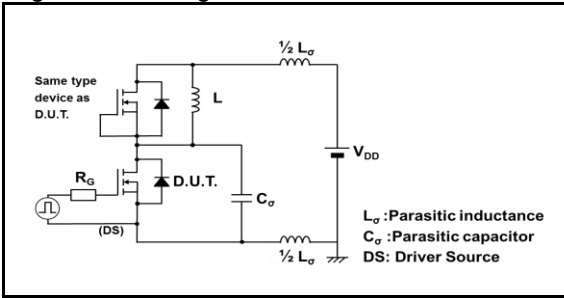


Fig.2-2 Waveforms for Switching Time

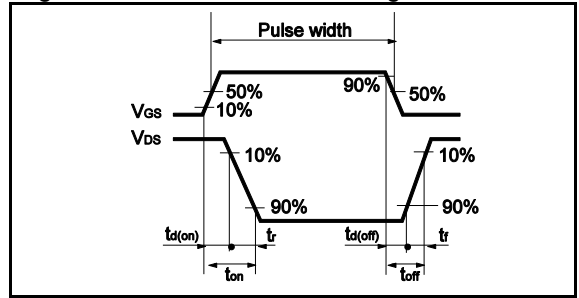


Fig.2-3 Waveforms for Switching Energy Loss

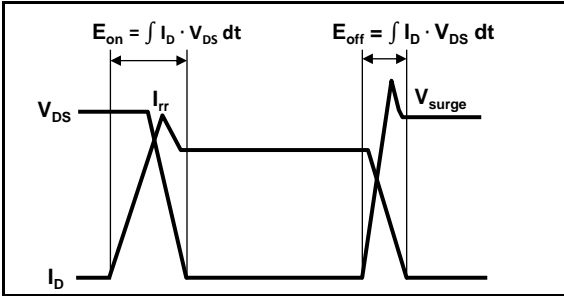


Fig.3-1 Reverse Recovery Time Measurement Circuit

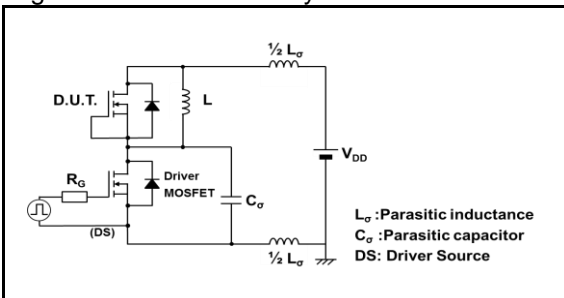
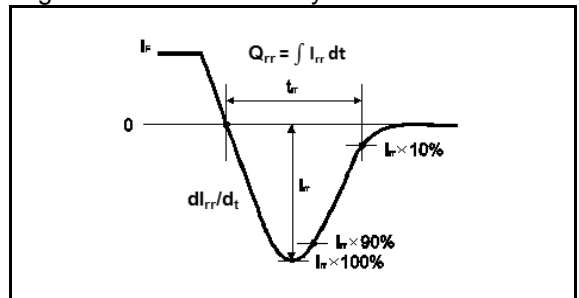


Fig.3-2 Reverse Recovery Waveform



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Part Number	SCT3105KR
Package	TO-247-4L
Unit Quantity	450
Minimum Package Quantity	30
Packing Type	Tube
Constitution Materials List	inquiry
RoHS	Yes